



Material Content Data Sheet



Sales Product Name		BTS50080-1TMA		Issued		25. September 2017		
MA#		MA001044086						
Package		PG-TO220-7-4		Weight*		1525.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.391	0.42	0.42	4188	4188
leadframe	non noble metal	iron	7439-89-6	0.910	0.06		597	
	inorganic material	phosphorus	7723-14-0	0.273	0.02		179	
	non noble metal	copper	7440-50-8	909.052	59.57	59.65	595813	596590
wire	non noble metal	aluminium	7429-90-5	2.194	0.14	0.14	1438	1438
encapsulation	organic material	carbon black	1333-86-4	8.858	0.58		5806	
	plastics	epoxy resin	-	97.440	6.39		63864	
	inorganic material	silicondioxide	60676-86-0	484.246	31.74	38.71	317386	387056
leadfinish	non noble metal	tin	7440-31-5	12.090	0.79	0.79	7924	7924
plating	non noble metal	nickel	7440-02-0	0.216	0.01		141	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	141
glue	plastics	Polyimide	26023-21-2	0.143	0.01	0.01	93	93
solder	noble metal	silver	7440-22-4	0.098	0.01		64	
	non noble metal	tin	7440-31-5	0.078	0.01		51	
	non noble metal	lead	7439-92-1	3.746	0.25	0.27	2455	2570
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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